AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (Canceled)

9. (Currently Amended) A semiconductor device test probe ~~having~~ comprising a tip portion for being urged against ~~a plurality of~~ an electrode ~~pads~~ pad of an integrated semiconductor device to establish an electrical ~~contacts~~ contact between the tip portion and the electrode ~~pads~~ pad for testing an operation of the semiconductor;

said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature r expressed by 10 $\mu m \leq r \leq 20$ μm, and said tip portion having a surface roughness equal to or less than 0.4μm.

10. (Currently Amended): A semiconductor device test probe ~~having~~ comprising a tip portion for being urged against ~~a plurality of~~ an electrode ~~pads~~ pad of an integrated semiconductor device to establish an electrical ~~contacts~~ contact between the tip portion and the electrode ~~pads~~ pad for testing an operation of the semiconductor;

said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature r expressed by 10$\mu m \leq r \leq 20\mu m$, said tip portion generating a shear deformation on the electrode pads, and said tip portion having a surface roughness equal to or less than 0.4μm.

11. (Currently Amended): A probe card having a plurality of probes which can be brought into contact with a plurality of electrode pads to test the semiconductor device, wherein the card comprises the probe of claim [[1]] 9 .

12. (Currently Amended): A probe card having a plurality of probes which can be brought into contact with a plurality of electrode pads to test the semiconductor device, wherein the card comprises the probe of claim [[2]] 10.